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Intel® Server Board S2600WT2R

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Specifications

Essentials	
Status	Launched
Launch Date	Q1'16
Expected Discontinuance	Q4'19
Limited 3-year Warranty	Yes
Extended Warranty Available for Purchase (Select Countries)	Yes
Additional Extended Warranty Details	Dual Processor Board Extended Warranty
# of QPI Links	2
Compatible Product Series	Intel® Xeon® Processor E5-2600 v4 Family
Board Form Factor	Custom 16.7" x 17"
Chassis Form Factor	Rack
Socket	Socket R3
Integrated Systems Available	Yes
Integrated BMC with IPMI	IPMI 2.0 with OEM extensions
Rack-Friendly Board	Yes
Embedded Options Available	No
TDP	145 W
Included Items	(1) Intel® Server Board S2600WT2R w/two 1Gb ports (Intel® Ethernet Controller I350)
Recommended Customer Price	N/A
Datasheet	Link
Board Chipset	(Intel® DH82029 PCH)
Description	A rack optimized server board supporting two Intel® Xeon® processor E5-2600 V3/V4 family up to 145W 24 DIMMs and two 1-Gb ethernet ports
Target Market	Cloud/Datacenter
Additional Information URL	Link

Memory Specifications	
Max Memory Size (dependent on memory type)	1.54 TB
Memory Types	DDR4 ECC RDIMM/LRDIMM 1600/1866/2133/2400
Max # of Memory Channels	8
Max Memory Bandwidth	153.6 GB/s
Physical Address Extensions	46-bit
Max # of DIMMs	24
ECC Memory Supported †	Yes

Graphics Specifications	
Integrated Graphics ‡	Yes

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PCN/MDDS Information

943786: [PCN](#) | [MDDS](#)

Graphics Output	VGA
Discrete Graphics	Supported

Expansion Options

PCI Express Revision	3.0
Max # of PCI Express Lanes	84
PCIe x4 Gen 3	1
PCIe x8 Gen 3	1
Connector for Intel® I/O Expansion Module x8 Gen 3	1
Connector for Intel® Integrated RAID Module	1

I/O Specifications

USB Revision	2.0 & 3.0
# of USB Ports	8
Total # of SATA Ports	10
RAID Configuration	SW RAID 0 1 10 optional 5
# of Serial Ports	2
# of LAN Ports	2
Integrated LAN	2x 1GbE
Firewire	No
Embedded USB (eUSB) Solid State Drive Option	Yes
Integrated SAS Ports	0
Integrated InfiniBand*	No

Package Specifications

Max CPU Configuration	2
Low Halogen Options Available	See MDDS

Advanced Technologies

Intel® Virtualization Technology for Directed I/O (VT-d) ‡	Yes
Intel® Remote Management Module Support	Yes
Intel® Node Manager	Yes
Intel® Quick Resume Technology	No
Intel® Quiet System Technology	No
Intel® HD Audio Technology	No
Intel® Matrix Storage Technology	No
Intel® Rapid Storage Technology	No
Intel® Rapid Storage Technology enterprise	Yes
Intel® Fast Memory Access	Yes
Intel® Flex Memory Access	Yes
Intel® I/O Acceleration Technology	Yes
Intel® Advanced Management Technology	Yes
Intel® Server Customization Technology	Yes
Intel® Build Assurance Technology	Yes
Intel® Efficient Power Technology	Yes
Intel® Quiet Thermal Technology	Yes

Intel® Data Protection Technology

Intel® AES New Instructions	Yes
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Intel® Platform Protection Technology

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Trusted Execution Technology ‡	Yes
 Intel® Transparent Supply Chain	
TPM Version	1.2/2.0

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact OEM for the BIOS that includes the latest Processor configuration update.


‡ This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality, performance, and other benefits of this feature may vary depending on system configuration.

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System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

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